DS07-10202-1E

High-Frequency Resonator

Piezoelectric Resonator (24 to 40 MHz)

FAR Family (C4 Series L Type)

■ DESCRIPTION

The C4 series (L Type) resonators apply to the frequency range 24 to 60 MHz.

They are fabricated on a lithium niobate (LiNaO₃) substrate, producing resonators with ultra compact and superior stability due to the high electromechanical coupling coefficient of the material.

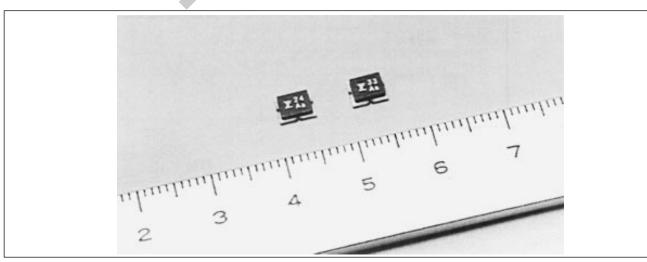
They use the third overtone resonance, so that they can oscilate at high frequency.

They include two loading capacitors inside and their package are chip type for surface mount. It contributes saving space and reducing mount cost.

■ FEATURES

- High frequency (24 to 60 MHz)
- Surface mount package (SMT)
- Suitable for the source of microcomputer clock
- Emboss-typed pack for automatic mounting
- Superior shock and vibration resistance, preventing damage during automatic mounting

■ PACKAGE



■ STANDARD CHARACTERISTICS

Series Parameter Series	C4 Series	Remarks				
Material	Lithium Niobate (LiNbO ₃)					
Frequency	24 to 40 MHz					
Standard frequency	See "■ Standard Frequency"					
Initial frequency deviation	Within ±0.5% (M)	The ±0.3% (K) version can also be produced.				
Temperature characteristic (–30°C to +85°C)	Within 0.5%	Reference temperature: +25°C				
Capacity of built-in capacitor	20±8 pF (standard)	10±4 pF are also available. Capacity is specified by Fujitsu, considering matching data with applied IC (mainly microcomputer)				
Aging stability	Within ±0.1%					
Operating temperature	−30°C to +85°C					
Storage temperature	−40°C to +100°C					
Standard measuring circuit	 Resonant frequency 1 MΩ C₁ C₂ Serial resonant resistance 	24 MHz to 40 MHz IC: MC74HCU04N × 2 • V cc = 5 V DC • R: Resonator • C 1, C 2: Loading capacitators (built-in)				
	$\begin{array}{c c} & & & \\ \hline \\ 75\Omega & & C_1 & C_2 \\ \hline \end{array}$	75Ω Measuring instrument: Network analyzer				

■ STANDARD FREQUENCY

Standard frequency (kHz)	Package size	Resonant resistance
24,000 kHz 33,869 kHz 40,000 kHz	L	75 Ω max. (Symbol: 2)

Note: Fujitsu can also develop applicable device in addition to standard devices if it's oscillation frequency is from 24 to 60 MHz.

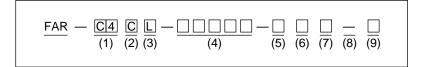
■ NOTES ON USE

- · Handle carefully
- Solder under the following conditions.
 - 5 seconds max. at 230°C (PCB)

Recommended preheating is 150°C for one minute in order not to apply extreme heat to the resonator.

- Avoid extreme fluctuations in temperature.
- There is no specific direction in resonator mounting.
- · Oscillation data should be examined when used in oscillation circuit with micon or other ICs.
- This is for reflow solder, not for flow solder.

■ PART NUMBERING SYSTEM



(1) Series

Series	Single crystal	Capacitator			
C4	LiNbO ₃	With built-in capacitator			

(2) Package Type

Specification	Туре
С	CHIP

(3) Package Type

Specification	Size
L	5.0 × 4.0 × 1.6

(4) Frequency

See "■ Standard Frequency."

(Example)

Unit: kHz (Specify in five digits.)

 $24.0~\text{MHz} \rightarrow 24000$

(5) Initial Frequency Deviation

Specification	Deviation
К	±0.3%
M	±0.5%

(6) Built-in Capacitor

Specification	Capacitance				
0	20±8 pF				
1	10±4 pF				

(7) Resonant Resistance

Specification	Resonant resistance
2	75Ω max.

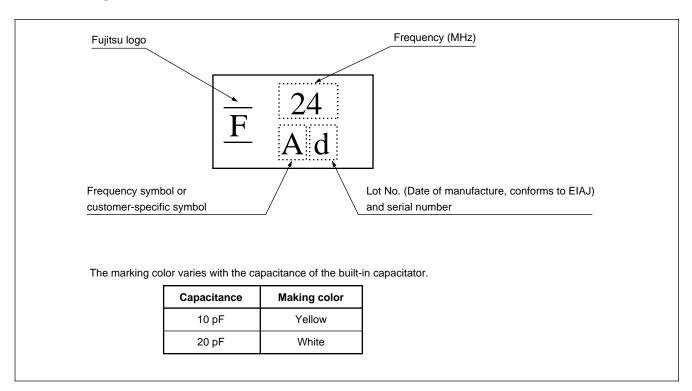
(8) User-specific Special Symbols

Specification	Description			
Name	No specifications, no taping specification			
_	No specifications, with taping specification			
A to Z	Serial number for custom design			

(9) Resonant Resistance

Specification	Description		
R	12 mm wide tape and reel		

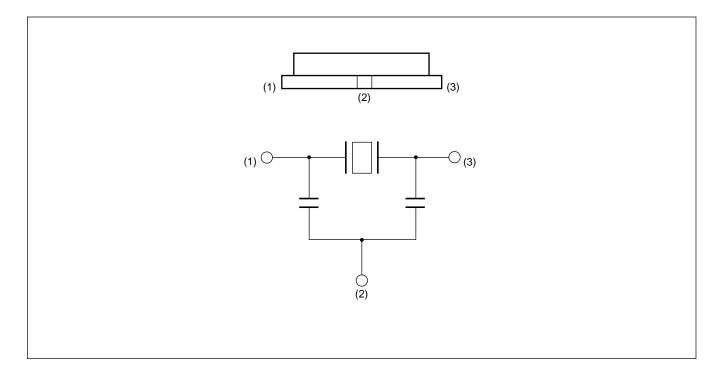
■ MARKING



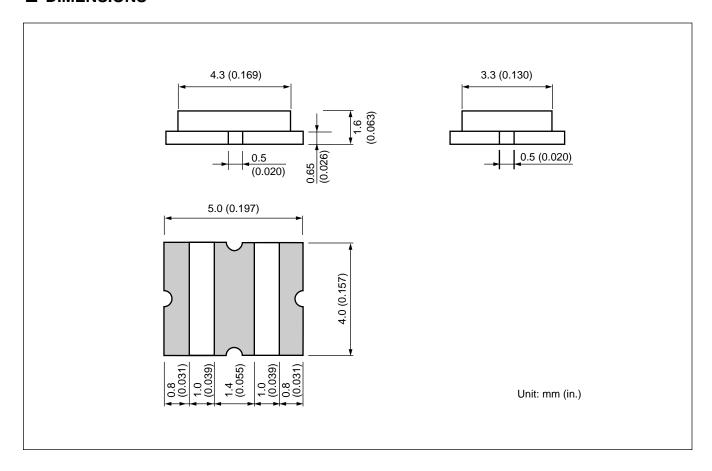
Data code (EIAJ standard) is specified as follows in four-year cycle.

Year	Month	Symbol	Year	Month	Symbol	Year	Month	Symbol	Year	Month	Symbol
	1	Α		1	N	1995 1999 2003	1	а	1996 2000 2004	1	n
	2	В		2	Р		2	b		2	ρ
	3	С		3	Q		3	c		3	q
	4	D		4	R		4	d		4	r
	5	Е	1998 2002	5	S		5	е		5	۵
1997	6	F		6	Т		6	f		6	t
2001	7	G		7	U		7	9		7	u
	8	Н		8	V		8	h		8	υ
	9	J		9	W		9	j		9	w
	10	K		10	Х		10	k		10	x
	11	L		11	Y		11	ℓ		11	y
	12	М		12	Z		12	m		12	3

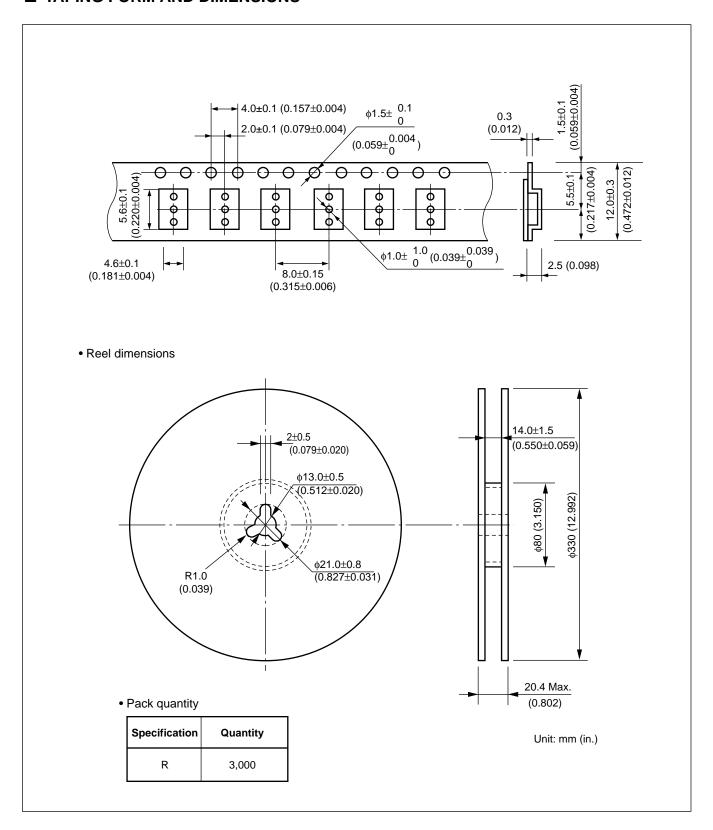
■ PIN ASSIGNMENT



■ DIMENSIONS



■ TAPING FORM AND DIMENSIONS



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